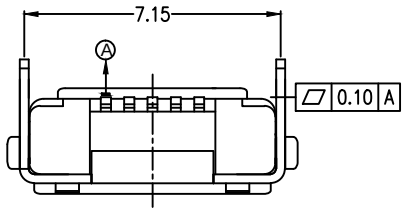
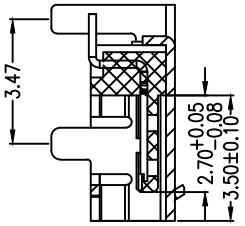
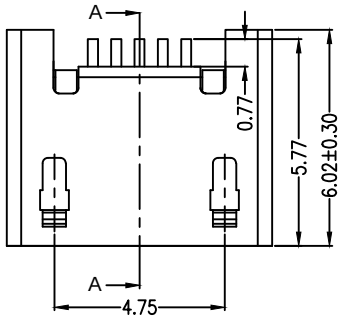
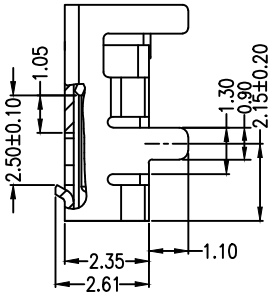
MAPX	MODIFICATION	DATE

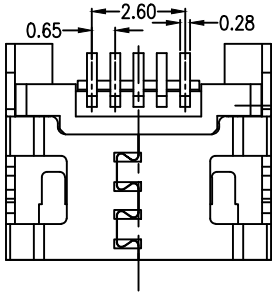


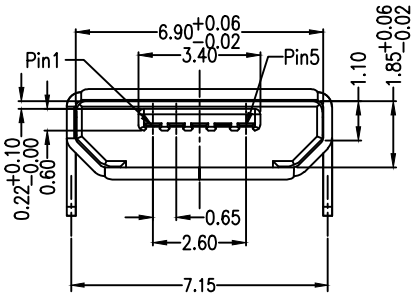


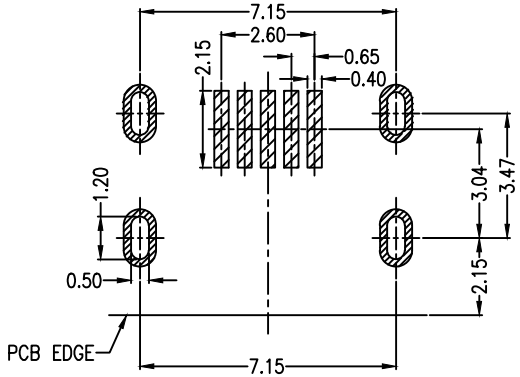
SECTION A-A











RECOMMANDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v−0

1.2 Contact: copper alloy,t=0.20mm

1.3 Shell: copper alloy or SUS,t=0.25mm

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: −30°C~80°C

???

PRODUCT CHART DWG

????? TOLERANCE UNLESS OTHERMSE

X.	±0.30	X.	±5.°
.X	±0.25	.X	±2.°
.XX	±0.20	.XX	±1.°
.XXX	±0.10	.XXX	±0.5°

深圳市精拓金电子有限公司

?? UNITS	MM	?? DRAWING	YANG	???? PRODUCT PART NO.	920-A62A2021S10106
?? SCALE	1:1	?? CHKD	???	???? PRODUCT NO.	MICRO 5P-F B型四脚插板7.2无卷边无柱端子加长0.75
?? DATE	2019.11.23	?? APPD	???	?? VIEW	?? VER / A0